

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	9123	((257/787,788,783,778) or (438/112,124,127,126,118,108)). CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/10 07:50
S2	1	("6703299").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/31 09:13
S3	12	((("5704116") or ("5817545") or ("5953814") or ("5998242") or ("6000924") or ("6094354") or ("6107123") or ("6168972") or ("6187613") or ("6207475") or ("6232152") or ("6326555")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/01 12:48
S4	9171	((257/787,788,783,778) or (438/112,124,127,126,118,108)). CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/03 12:22
S5	303	S4 and (die IC chip integrated adj circuit) and (substrate mount platform base) and (underfill) and (wire interconnect electrical adj connection) and (curing heat treating) and (removing)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/11 14:49
S6	9171	((257/787,788,783,778) or (438/112,124,127,126,118,108)). CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/01 17:56
S7	275	S6 and (die IC chip integrated adj circuit) and (substrate mount platform base) and (underfill) and (wire interconnect electrical adj connection) and (curing heat treating) and (removing) and (film adhesive tape)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/04 12:31
S8	9171	((257/787,788,783,778) or (438/112,124,127,126,118,108)). CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/02 17:12
S9	888	S8 and (die IC chip integrated adj circuit) and (substrate mount platform base) and (underfill) and (wire interconnect electrical adj connection) and (curing heat treating)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/03 12:02
S10	1	("6703299").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/03 11:46
S11	9175	((257/787,788,783,778) or (438/112,124,127,126,118,108)). CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/03 12:04
S12	9175	((257/787,788,783,778) or (438/112,124,127,126,118,108)). CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/03 12:27

S13	9175	((257/787,788,783,778) or (438/112,124,127,126,118,108)). CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/03 15:46
S14	14311876	S13 and (die IC chip integrated adj circuit) and (substrate mount platform base) and (underfill) and (wire interconnect electrical adj connection) and (curing heat treating) and (removing) and (film adhesive tape) @ay<"02092004"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/03 15:48
S15	14311876	S13 and (die IC chip integrated adj circuit) and (substrate mount platform base) and (underfill) and (wire interconnect electrical adj connection) and (curing heat treating) and (removing) and (film adhesive tape) @ay<"20040209"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/03 15:49
S16	275	S13 and (die IC chip integrated adj circuit) and (substrate mount platform base) and (underfill) and (wire interconnect electrical adj connection) and (curing heat treating) and (removing) and (film adhesive tape) and @ay<="20040209"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/03 16:38
S17	38	S13 and (die IC chip integrated adj circuit) and (substrate mount platform base) and (underfill) and (wire interconnect electrical adj connection) and (curing heat treating) and (removing) and (film adhesive tape) and (tacky non-tacky non adj tacky)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/03 16:51
S18	25	S13 and (die IC chip integrated adj circuit) and (substrate mount platform base) and (underfill) and (wire interconnect electrical adj connection) and (curing heat treating) and (removing) and ((film adhesive tape) with (tacky non-tacky non adj tacky))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/03 16:52
S19	3	S12 and (die IC chip integrated adj circuit) and (substrate mount platform base) and (underfill) and (wire interconnect electrical adj connection) and (curing heat treating) and (removing) and mold adj press	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/03 17:56
S20	1	("6326555").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/04 09:21

S21	1	("6232152").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/04 09:21
S22	9175	((257/787,788,783,778) or (438/112,124,127,126,118,108)). CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/04 12:41
S23	234	S22 and (die IC chip integrated adj circuit) and (substrate mount platform base) and (underfill encapsul\$5) and (wire interconnect electrical adj connection) and (curing heat treating) and ((removing) with (film adhesive tape bonding adj sheet))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/04 13:20
S24	660	S22 and (die IC chip integrated adj circuit) and (substrate mount platform base) and (underfill encapsul\$5) and (wire interconnect electrical adj connection) and (curing heat treating) and ((remov\$3) with (film adhesive tape bonding adj sheet))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/10 17:02
S25	223	S22 and (die IC chip integrated adj circuit) and (substrate mount platform base) and (underfill encapsul\$5) and (wire interconnect electrical adj connection) and ((curing heat treating) same ((remov\$3) with (film adhesive tape bonding adj sheet)))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/10 17:11
S26	9175	((257/787,788,783,778) or (438/112,124,127,126,118,108)). CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/04 17:34
S27	1999	S26 and (die IC integrated adj circuit chip) and (mold press mold adj press) and (film tape adhesive) and remov\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/04 17:36
S29	2154	((228/180.22) or (438/464,977, FOR.485)).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/10 07:51
S30	9193	((257/787,788,783,778) or (438/112,124,127,126,118,108)). CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/10 07:51
S31	258	S29 and S30	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/10 07:51

S32	7	((S29 S30) and ((removable temporary) with underfill) and (curing cure cured heat adj treat\$3 heat-treat\$3 anneal\$3 baked baking bake)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/10 08:07
S33	43	((S29 S30) and ((removable temporary) with (tape adhesive film)) and (curing cure cured heat adj treat\$3 heat-treat\$3 anneal\$3 baked baking bake) and underfill	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/10 08:08
S34	4540	(die IC chip integrated adj circuit) and (substrate mount platform base) and (underfill encapsulat\$3) and (wire interconnect\$3 electrical adj connection) and (cur\$3 heat\$3) and ((remov\$3) with (film adhesive tape bonding adj sheet))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/11 08:12
S35	9193	((257/787,788,783,778) or (438/112,124,127,126,118,108)). CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/11 08:13
S36	2154	((228/180.22) or (438/464,977, FOR.485)).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/11 08:13
S37	9193	((257/787,788,783,778) or (438/112,124,127,126,118,108)). CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/11 08:13
S38	762	(S35 S36 S37) and (die IC chip integrated adj circuit) and (substrate mount platform base) and (underfill encapsulat\$3) and (wire interconnect\$3 electrical adj connection) and (cur\$3 heat\$3) and ((remov\$3) with (film adhesive tape bonding adj sheet))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/11 10:29
S39	1	("5439162").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/11 11:32
S40	1	("6940181").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/11 11:38
S41	1	("6428650").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/11 11:38
S42	1	("20010040298").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/11 14:49